1.5 A, 30 V, Schottky Barrier Diode

These Schottky barrier diodes are optimized for low forward voltage drop and low leakage current and are offered in a Chip Scale Package (CSP) to reduce board space. The low thermal resistance enables designers to meet the challenging task of achieving higher efficiency and meeting reduced space requirements.

Features

- Low Forward Voltage Drop -530 mV (Typ.) @ $I_F = 1.5 \text{ A}$
- Low Reverse Current 20 μ A (Typ.) @ $V_R = 30 \text{ V}$
- 1.5 A of Continuous Forward Current
- ESD Rating Human Body Model: Class 3B
 - Machine Model: Class C
- High Switching Speed
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applications

- LCD and Keypad Backlighting
- Camera Photo Flash
- Buck and Boost dc-dc Converters
- Reverse Voltage and Current Protection
- Clamping & Protection

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Reverse Voltage	V_R	30	V
Forward Current (DC)	IF	1.5	Α
Forward Surge Current (60 Hz @ 1 cycle)	I _{FSM}	12	Α
Repetitive Peak Forward Current (Pulse Wave = 1 sec, Duty Cycle = 66%)	I _{FRM}	2.5	Α
ESD Rating: Human Body Model Machine Model	ESD	> 8 > 400	kV V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

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PIN 1

DSN2 (0402) CASE 152AE 4MM

MARKING DIAGRAM

4M = Specific Device Code Y = Year Code

PIN CONNECTIONS



ORDERING INFORMATION

Device	Package	Shipping†
NSR15304NXT5G	DSN2 (Pb-Free)	5000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Min	Тур	Max	Unit
Thermal Resistance Junction-to-Ambient (Note 1) Total Power Dissipation @ T _A = 25°C	R _{θJA} P _D			260 480	°C/W mW
Thermal Resistance Junction-to-Ambient (Note 2) Total Power Dissipation @ T _A = 25°C	R _{θJA} P _D			100 1.25	°C/W W
Storage Temperature Range	T _{stg}			-40 to +125	°C
Junction Temperature	TJ			+150	°C

- 1. Mounted onto a 4 in square FR-4 board 50 mm sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.
- 2. Mounted onto a 4 in square FR-4 board 650 mm sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.

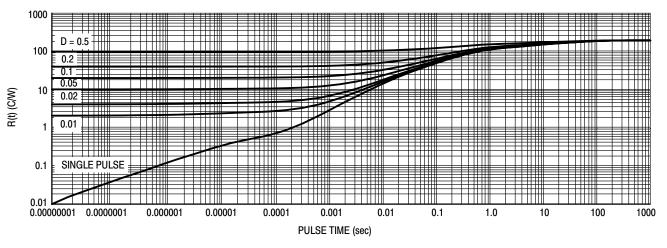


Figure 1. Thermal Response (Note 1)

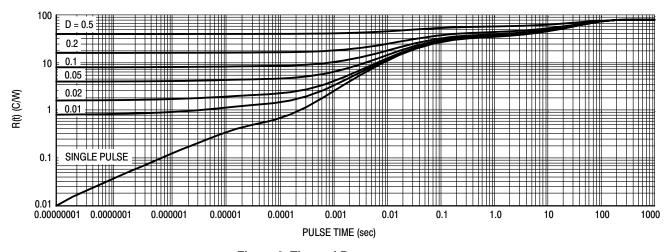
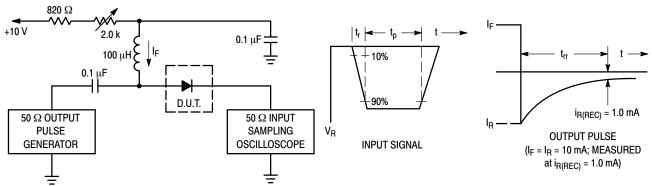


Figure 2. Thermal Response (Note 2)

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic		Min	Тур	Max	Unit
Reverse Leakage (V _R = 10 V) (V _R = 20 V)	I _R	_ _	2.0 20	10 80	μΑ
Forward Voltage (I _F = 10 mA) (I _F = 100 mA) (I _F = 500 mA) (I _F = 1.0 A) (I _F = 1.5 A)	V _F	- - - - -	270 340 420 480 530	310 380 460 520 580	mV
Total Capacitance (V _R = 2.0 V, f = 1.0 MHz)	C _T	_	60	-	pF
Reverse Recovery Time ($I_F = I_R = 10 \text{ mA}$, $I_{R(REC)} = 1.0 \text{ mA}$, Figure 3)	t _{rr}	-	25	-	ns
Peak Forward Recovery Voltage (I _F = 100 mA, t _r = 20 ns, Figure 4)	V_{FRM}	-	492	-	mV

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.



Notes: 1. A 2.0 k Ω variable resistor adjusted for a Forward Current (I_F) of 10 mA.

2. Input pulse is adjusted so $I_{R(peak)}$ is equal to 10 mA.

3. t_p » t_{rr}

Figure 3. Recovery Time Equivalent Test Circuit

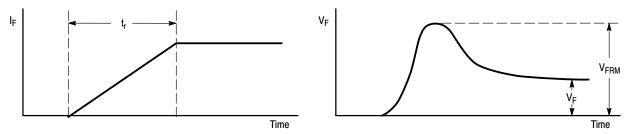
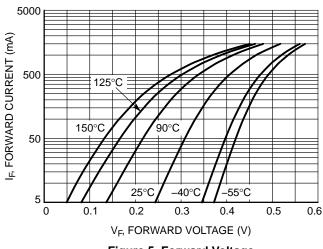


Figure 4. Peak Forward Recover Voltage Definition

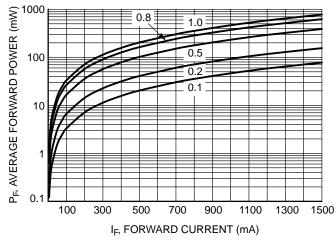
TYPICAL CHARACTERISTICS



100K 150°C 100000 IR, REVERSE CURRENT (µA) 10K 125°C 90°C 10 25°C 40°C 55°C 0.00001 5 15 20 25 30 V_R, REVERSE VOLTAGE (V)

Figure 5. Forward Voltage

Figure 6. Leakage Current



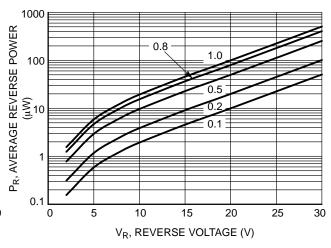


Figure 7. Average Forward Power Dissipation

Figure 8. Average Reverse Power Dissipation

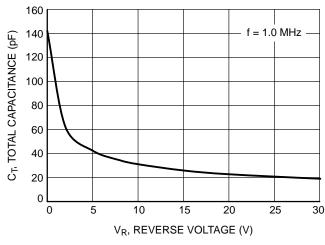


Figure 9. Total Capacitance

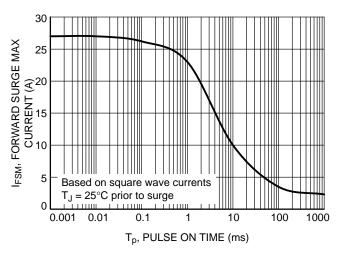
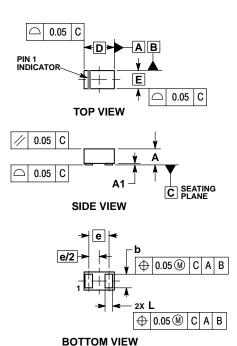


Figure 10. Forward Surge Maximum

PACKAGE DIMENSIONS

DSN2, 1.0x0.6, 0.65P, (0402) CASE 152AE ISSUE A

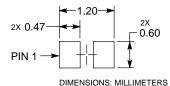


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.

	MILLIMETERS			
DIM	MIN	MAX		
Α	0.25	0.31		
A1		0.05		
b	0.45	0.55		
D	1.00 BSC			
E	0.60 BSC			
е	0.65 BSC			
L	0.20	0.30		

RECOMMENDED SOLDER FOOTPRINT*



See Application Note AND8398/D for more mounting details

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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